

US00D573110S

(12) **United States Design Patent**
Otsuki et al.

(10) **Patent No.:** **US D573,110 S**
(45) **Date of Patent:** **** Jul. 15, 2008**

(54) **HEAT SINK**

2007/0277957 A1* 12/2007 Wu et al. 165/80.3

(75) Inventors: **Takaya Otsuki**, Kyoto (JP); **Takamasa Yamashita**, Kyoto (JP); **Akira Hirakawa**, Kyoto (JP)

(73) Assignee: **Nidec Corporation**, Kyoto (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/282,736**

(22) Filed: **Jul. 27, 2007**

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Classification Search** D13/179;
165/80.3, 104.33, 151, 122, 185; 257/706,
257/707, 718-722; 361/687, 695, 697, 700,
361/702, 704, 709, 710, 711, 719

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,519,574	A	5/1996	Kodama et al.	
6,269,864	B1 *	8/2001	Kabadi	165/80.3
6,411,510	B2	6/2002	Sasa et al.	
6,470,962	B1 *	10/2002	Pao	165/80.3
D465,462	S	11/2002	Hsieh	
D465,771	S	11/2002	Hsieh	
6,480,383	B2	11/2002	Kodaira et al.	
6,480,387	B1 *	11/2002	Lee et al.	361/704
D474,754	S	5/2003	Tan et al.	
6,621,704	B1 *	9/2003	Liu	361/704
D481,017	S	10/2003	Hsia et al.	
6,976,525	B2 *	12/2005	Lin	165/80.3
2003/0121643	A1 *	7/2003	Connors	165/80.3
2005/0072558	A1 *	4/2005	Whitney et al.	165/80.3
2006/0056159	A1 *	3/2006	Lee et al.	361/709
2007/0074857	A1 *	4/2007	Xia et al.	165/104.33

FOREIGN PATENT DOCUMENTS

JP	D1091315	S	11/2000
JP	D1091551	S	11/2000
JP	D1091552	S	11/2000
JP	D1168617	S	3/2003
JP	D1168855	S	3/2003
JP	D1205085	S	5/2004

OTHER PUBLICATIONS

“Weekly Ascii”, Jun. 22, 2004, vol. 494, p. 156, published by Ascii Corporation, received by National Center for Industrial Property Information and Training on Jun. 8, 2004.

Official communication issued in the counterpart Japanese Application No. 2006-008877; mailed on Oct. 13, 2007.

Otsuki et al.; “Fan”; U.S. Appl. No. 29/249,373, filed Oct. 4, 2006.

* cited by examiner

Primary Examiner—Selina Sikder

(74) *Attorney, Agent, or Firm*—Keating & Bennett, LLP

(57) **CLAIM**

The ornamental design for a heat sink, as shown and described.

DESCRIPTION

FIG. 1 is a front elevation view of a heat sink according to our new design;

FIG. 2 is a rear elevation view thereof;

FIG. 3 is a right side elevation view thereof;

FIG. 4 is a left side elevation view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a perspective view thereof; and,

FIG. 8 is another perspective view thereof.

1 Claim, 8 Drawing Sheets

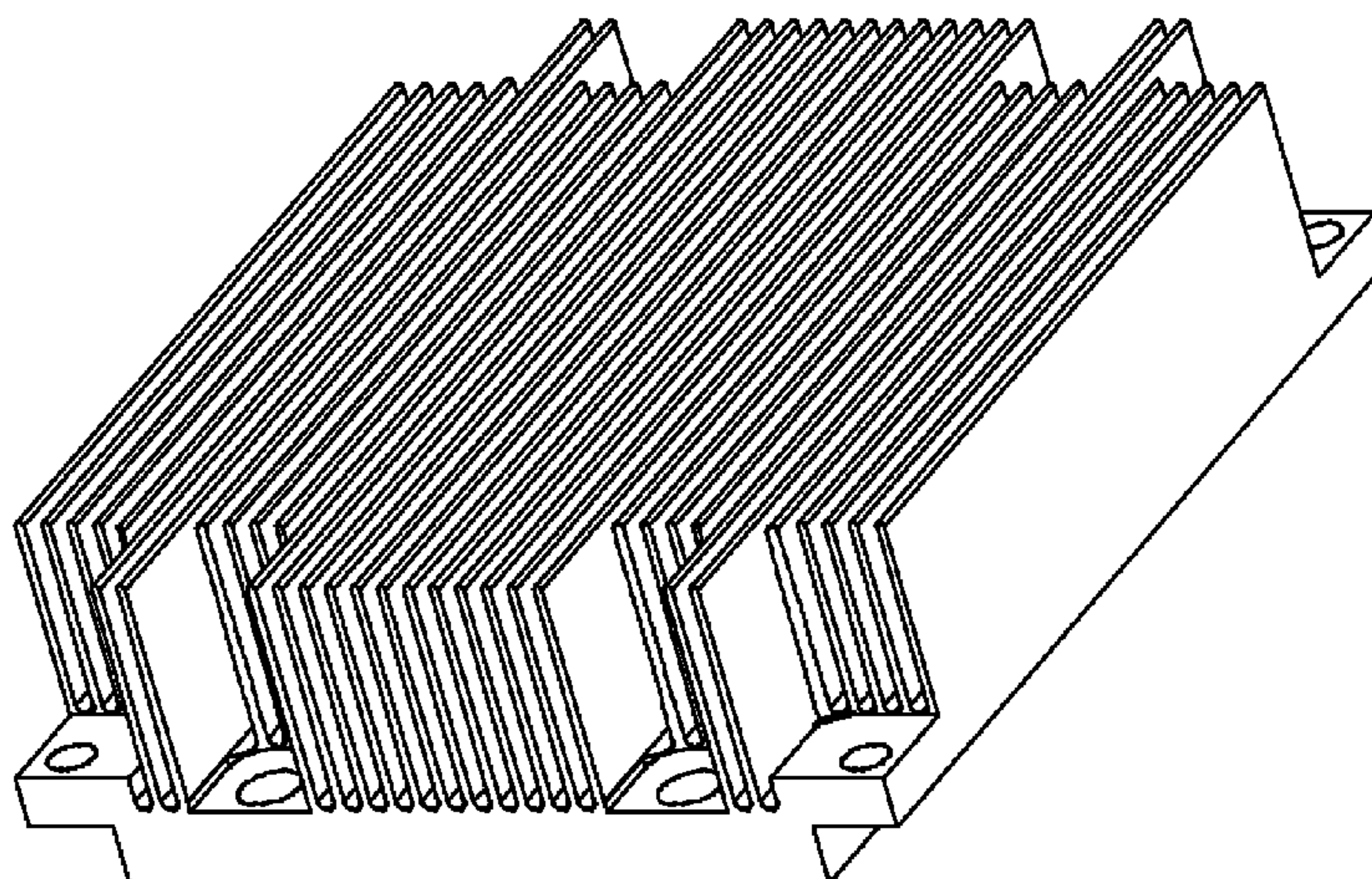


FIG. 1

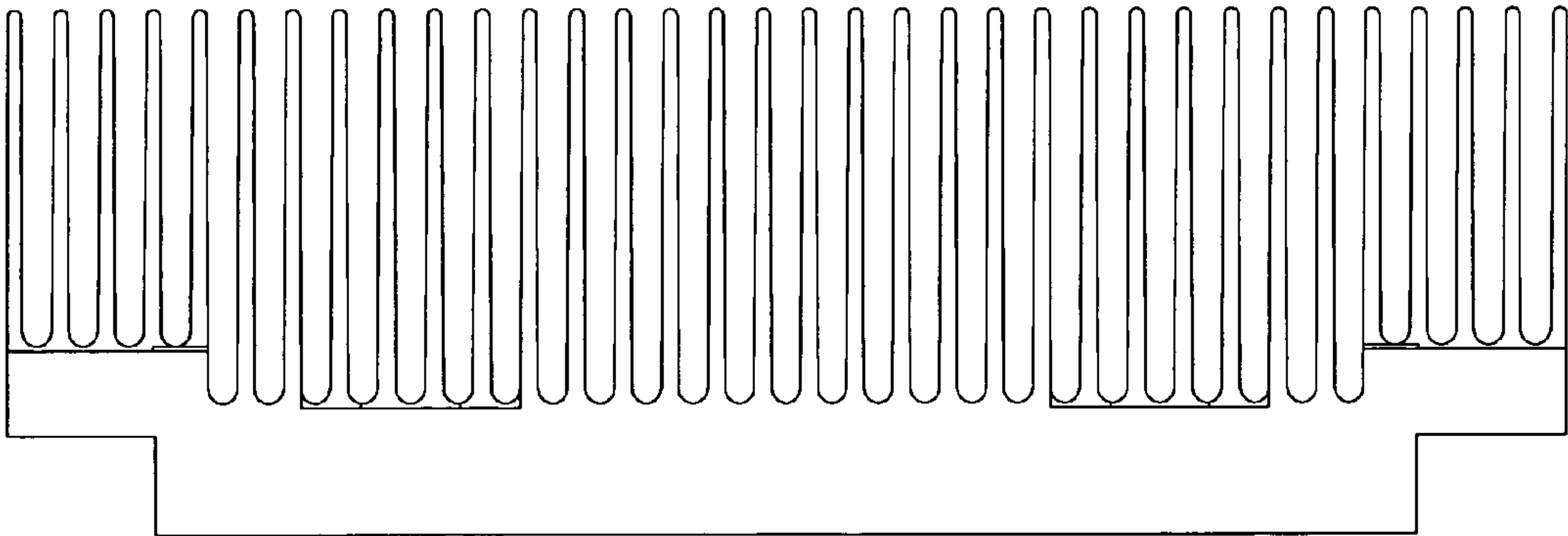


FIG. 2

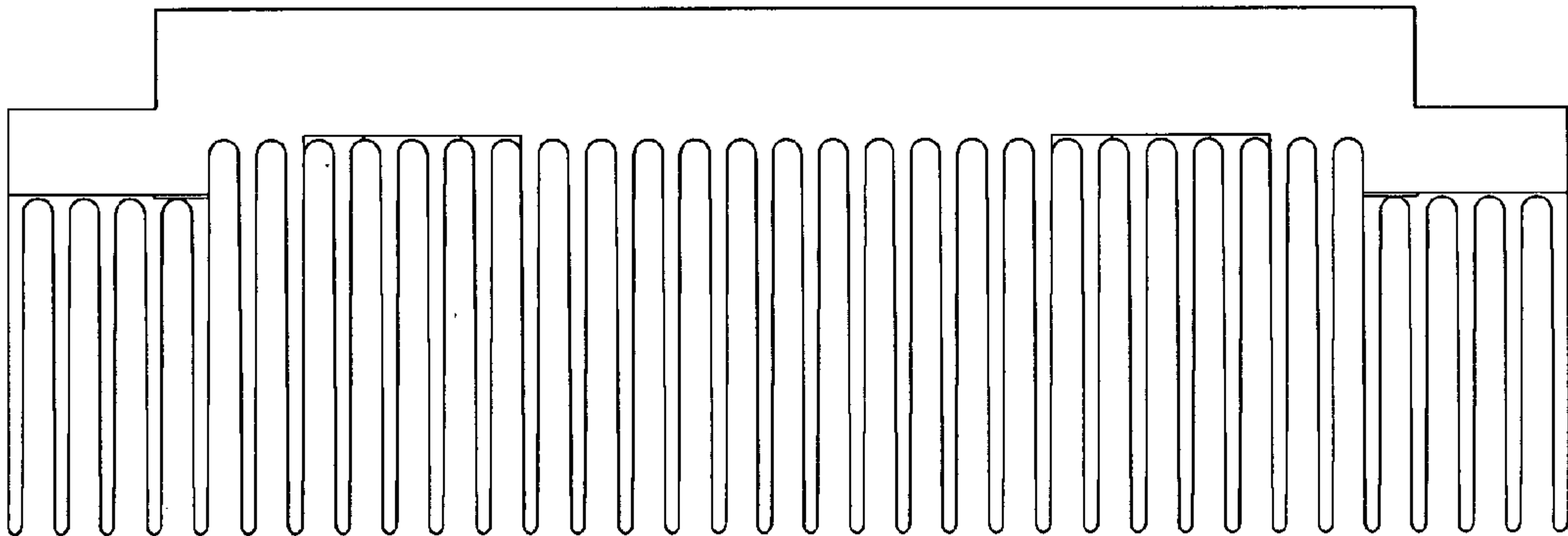


FIG. 3

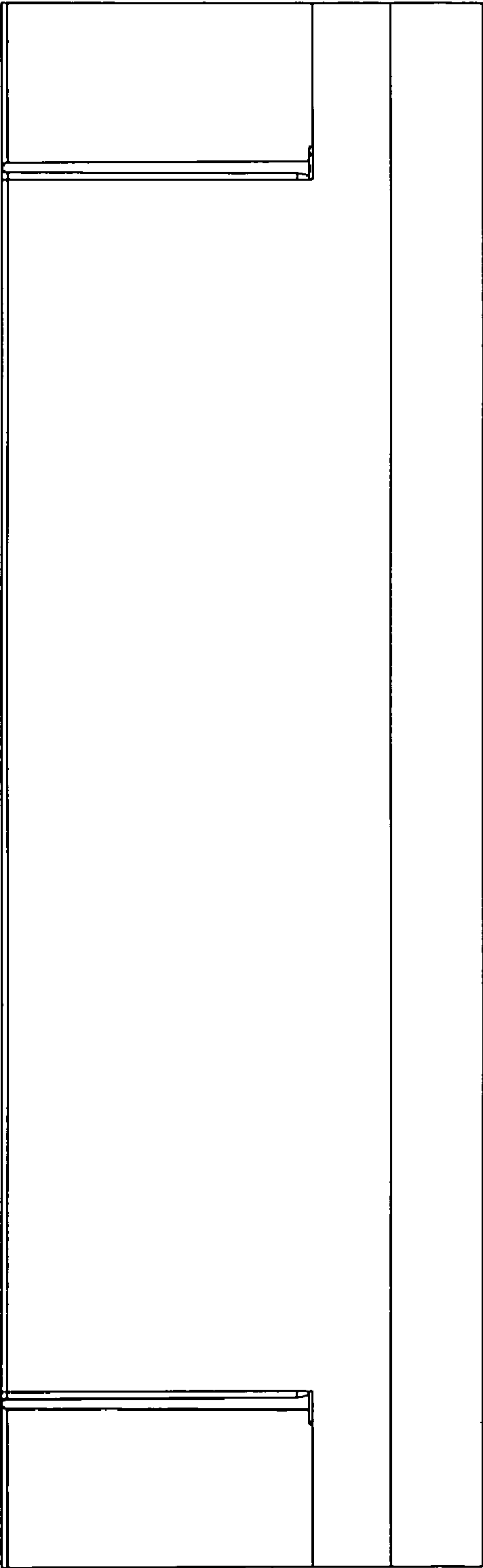


FIG. 4

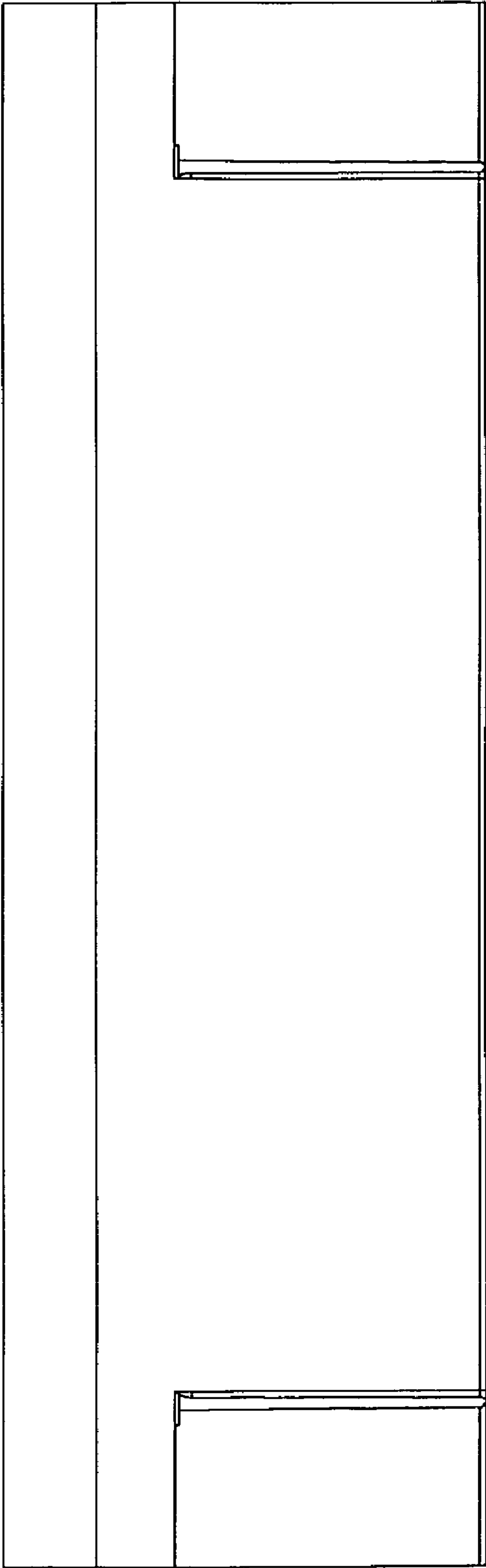


FIG. 5

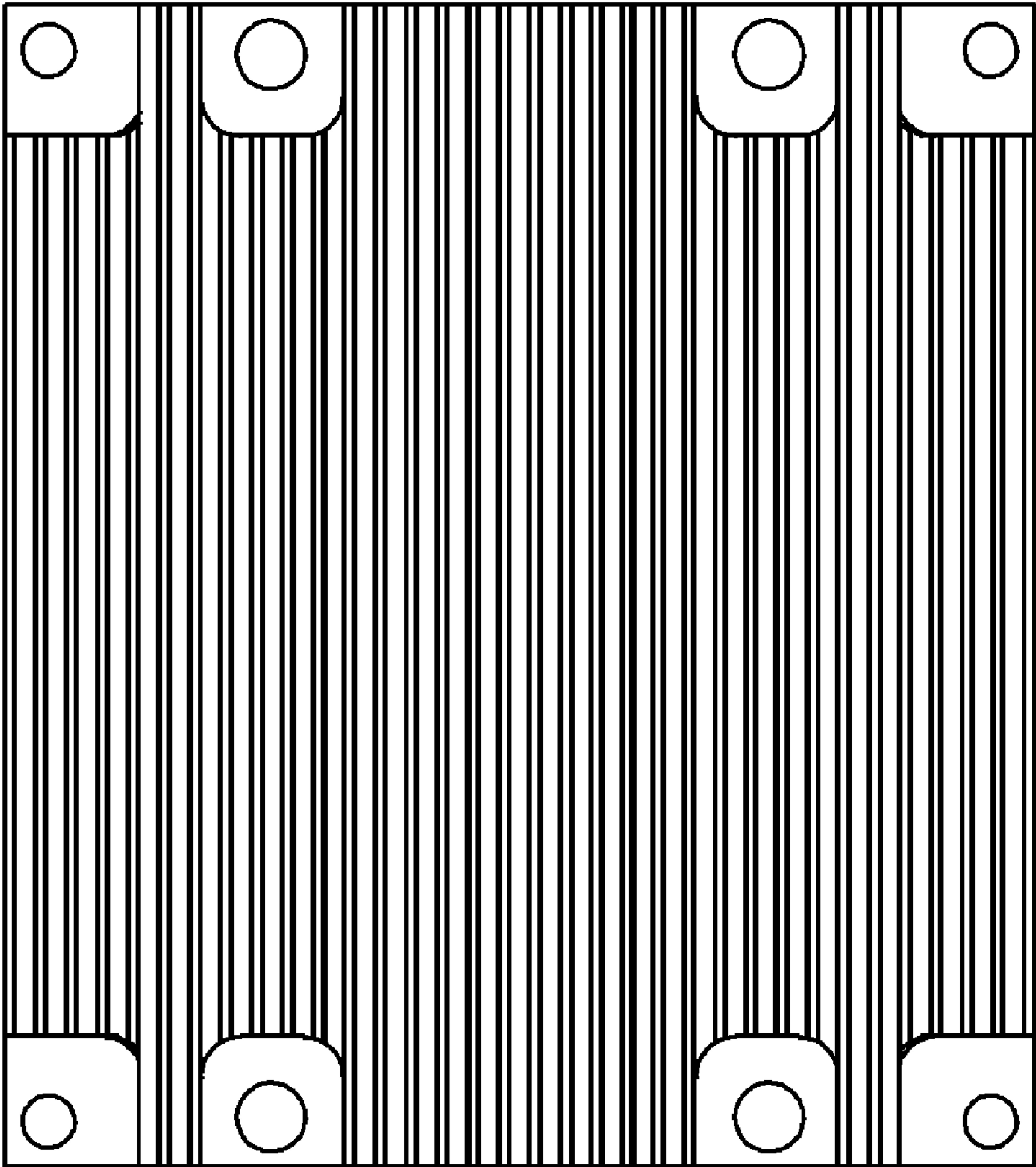


FIG. 6

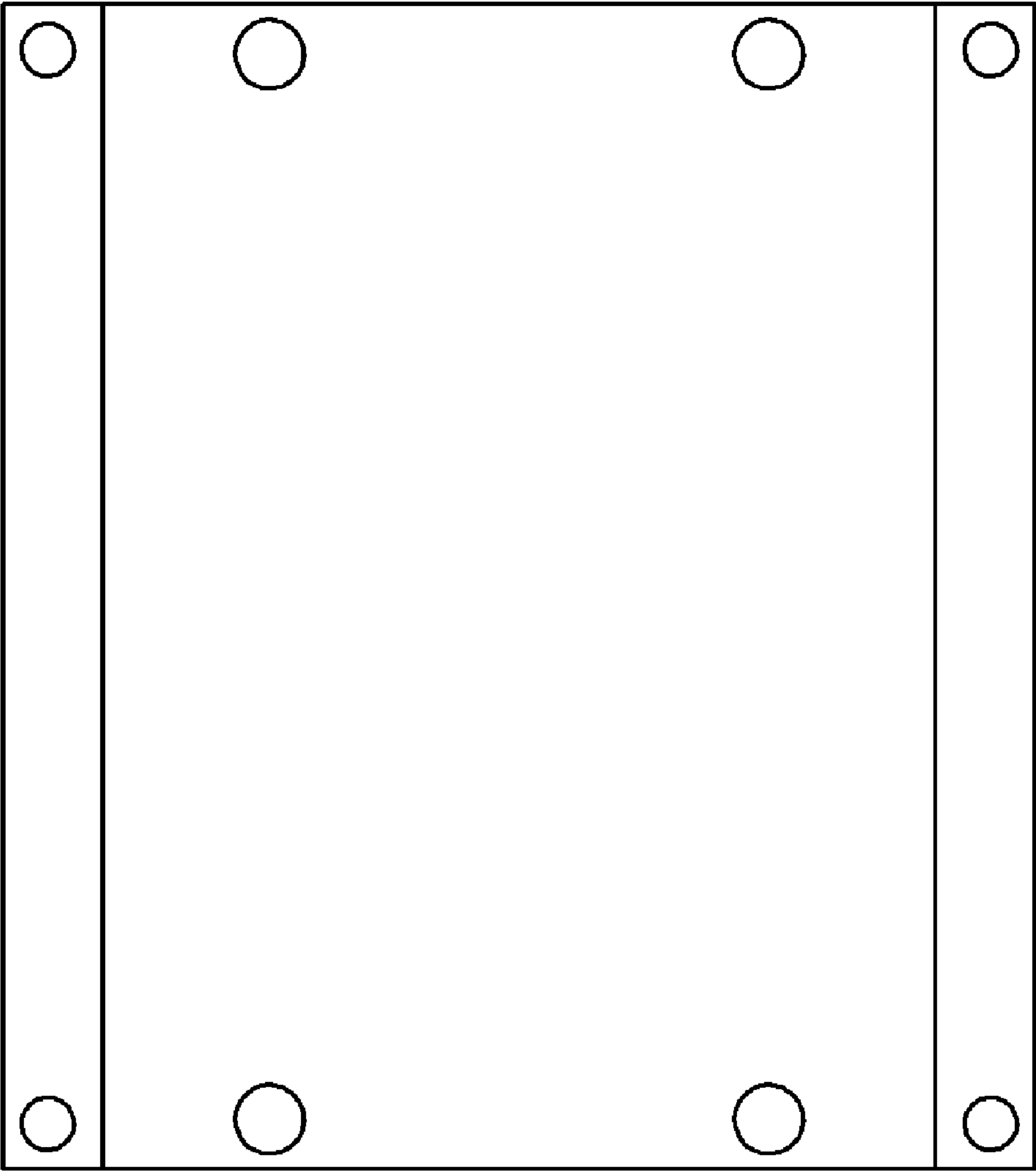


FIG. 7

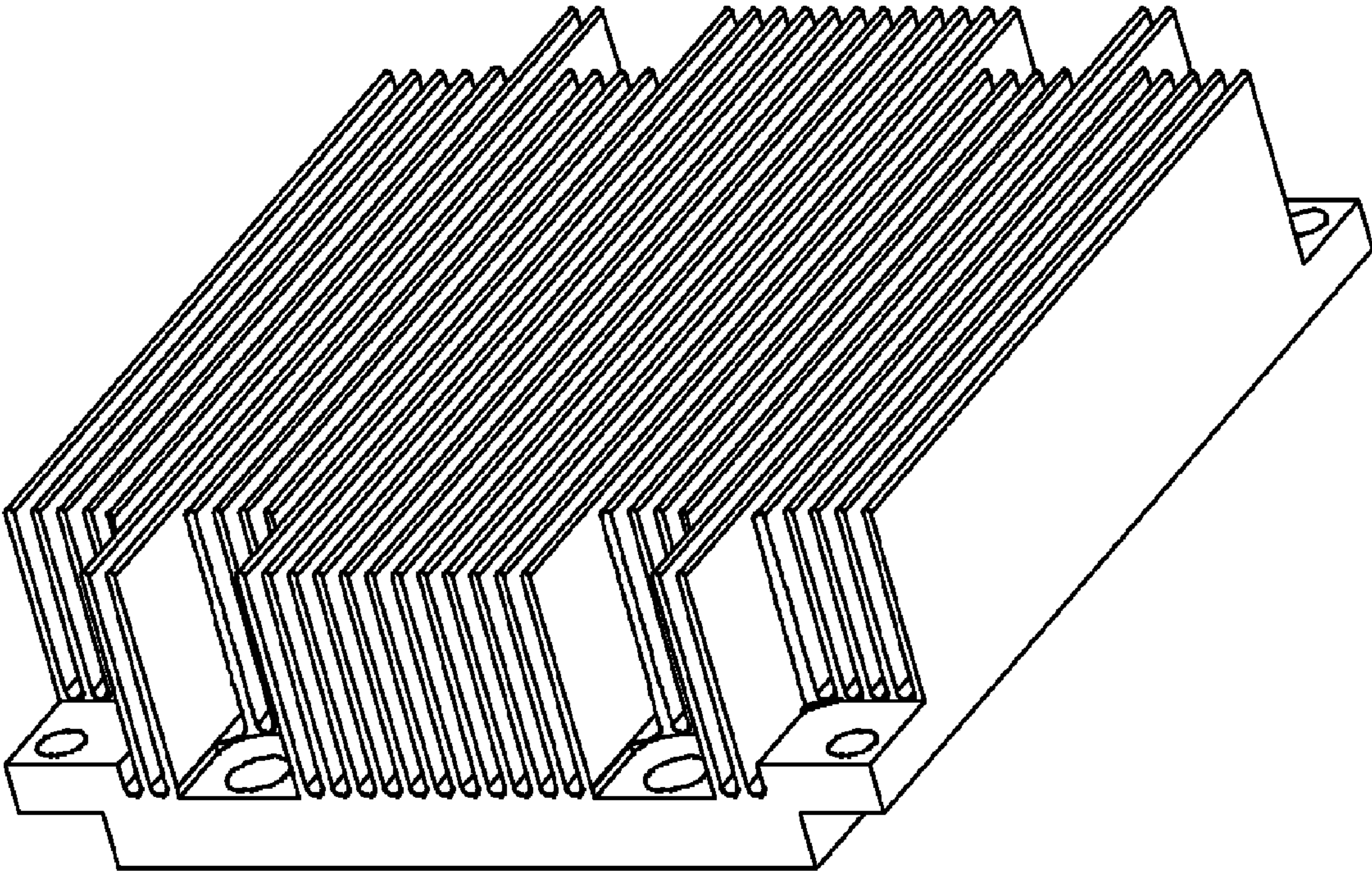


FIG. 8

